

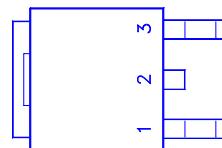
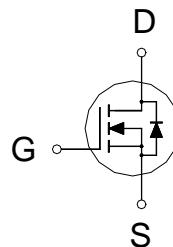
NIKO-SEM**N-Channel Enhancement Mode
Field Effect Transistor****P0425HDB**

TO-252

Halogen-Free & Lead-Free

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
250V	1.1 Ω	4A

**100% UIS tested****ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	V_{DS}	250	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ²	I_D	4	A
		2.4	
Pulsed Drain Current ^{1, 2}	I_{DM}	15	A
Avalanche Current ³	I_{AS}	0.6	
Avalanche Energy ³	E_{AS}	0.2	mJ
Power Dissipation	P_D	43	W
		17	
Operating Junction & Storage Temperature Range	T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$	2.9	62.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$			

¹Pulse width limited by maximum junction temperature.²Limited only by maximum temperature allowed³ $V_{DD} = 50\text{V}$, $L = 1\text{mH}$, starting $T_J = 25^\circ\text{C}$ **ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)**

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}$, $I_D = 250\mu\text{A}$	250			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$	1	2.1	3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}$, $V_{GS} = \pm 20\text{V}$			± 100	nA

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Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 250V, V_{GS} = 0V, T_C = 25^\circ C$ $V_{DS} = 200V, V_{GS} = 0V, T_C = 100^\circ C$			1	μA
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 2A$		0.81	1.1	Ω
		$V_{GS} = 4.5V, I_D = 2A$		0.98	1.7	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 10V, I_D = 2A$		3		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		170		pF
Output Capacitance	C_{oss}			42		
Reverse Transfer Capacitance	C_{rss}			10		
Total Gate Charge ²	Q_g	$V_{DD} = 200V, I_D = 4A, V_{GS} = 10V$		6.2		nC
Gate-Source Charge ²	Q_{gs}			1		
Gate-Drain Charge ²	Q_{gd}			2.7		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DD} = 125V, I_D = 4A, V_{GS} = 10V$		10		nS
Rise Time ²	t_r			6		
Turn-Off Delay Time ²	$t_{d(off)}$			14		
Fall Time ²	t_f			3		

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)

Continuous Current ³	I_S			4	A
Forward Voltage ¹	V_{SD}	$I_F = 4A, V_{GS} = 0V$		1.5	V
Reverse Recovery Time	t_{rr}	$I_F = 4A, dI_F/dt = 100A / \mu S$		115	nS
Reverse Recovery Charge	Q_{rr}			370	nC

¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.³Pulse width limited by maximum junction temperature.

NIKO-SEM

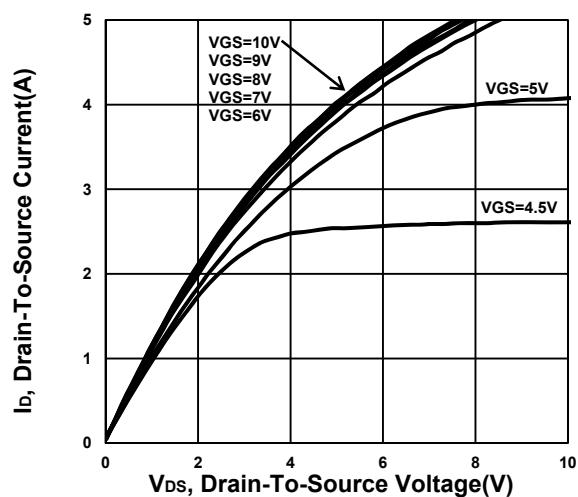
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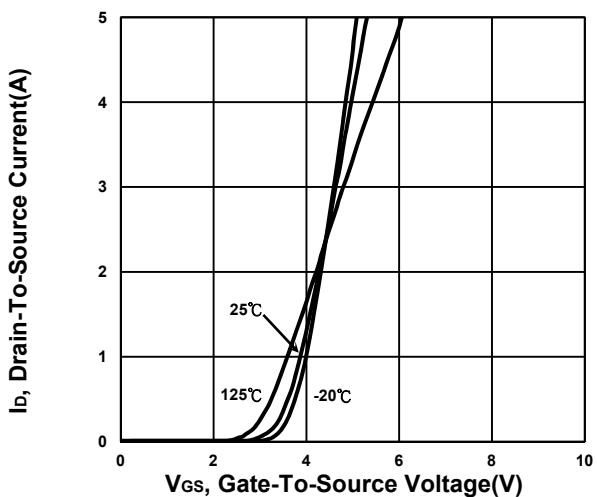
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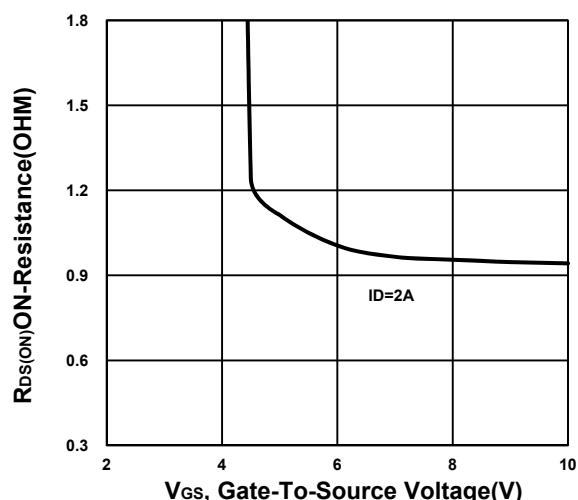
Output Characteristics



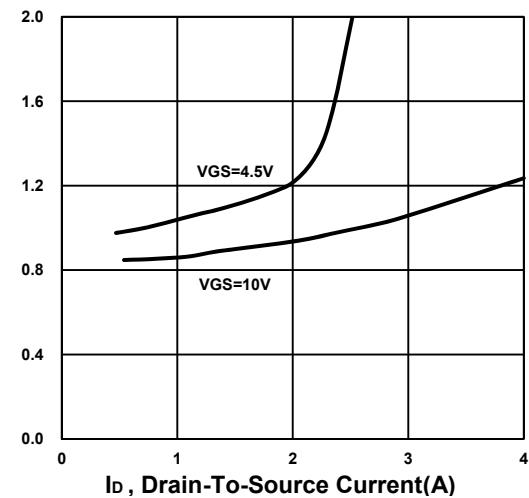
Transfer Characteristics



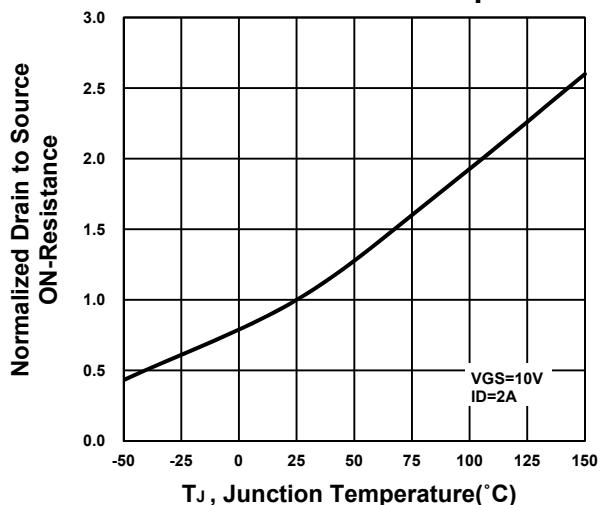
On-Resistance VS Gate-To-Source



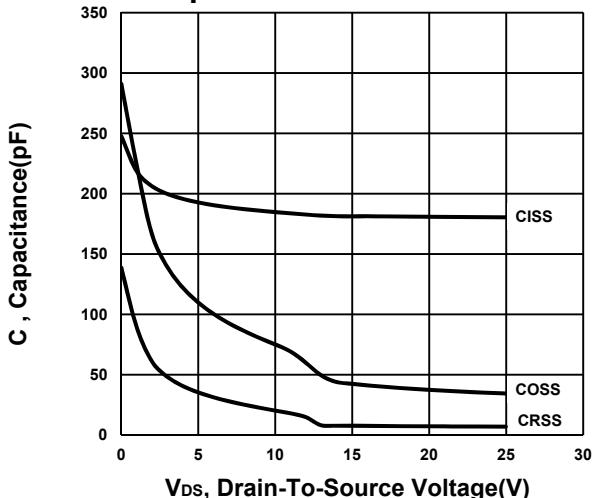
On-Resistance VS Drain Current



On-Resistance VS Temperature



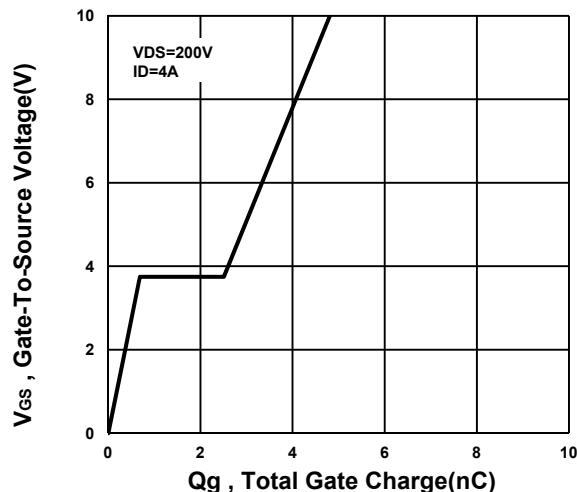
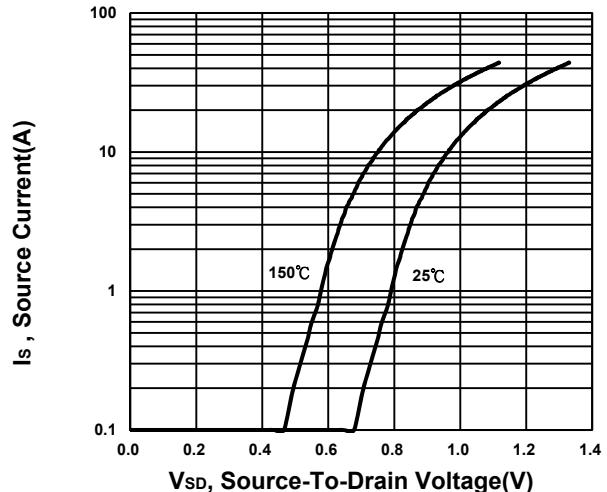
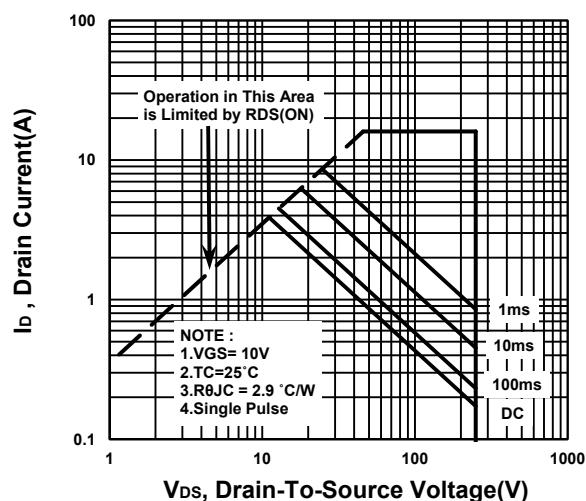
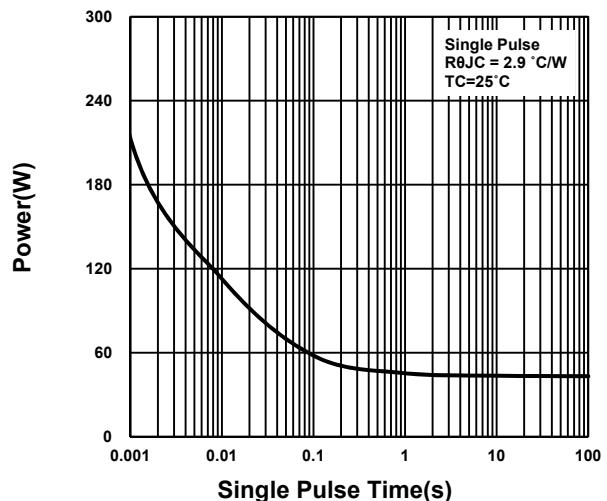
Capacitance Characteristic



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Gate charge Characteristics**Source-Drain Diode Forward Voltage****Safe Operating Area****Single Pulse Maximum Power Dissipation****Transient Thermal Response Curve**